



DIM750ASM65-TS000

Replaces DS6171-7

Single Switch IGBT Module

DS6171-8 August 2024 (LN43551)

FEATURES

- 10µs Short Circuit Withstand
- High Thermal Cycling Capability
- Soft Punch Through Silicon
- Isolated AISiC Base with AIN Substrates
- Lead Free Construction

APPLICATIONS

- High Reliability Inverters
- Motor Controllers
- Traction Drives
- Choppers

The Powerline range of high power modules includes half bridge, chopper, dual, single and bi-directional switch configurations covering voltages from 600V to 6500V and currents up to 2400A.

The DIM750ASM65-TS000 is a single switch 6500V, soft punch through n-channel enhancement mode, insulated gate bipolar transistor (IGBT) module. The IGBT has a wide reverse bias safe operating area (RBSOA) plus 10 μ s short circuit withstand. This device is optimised for traction drives and other applications requiring high thermal cycling capability.

The module incorporates an electrically isolated base plate and low inductance construction enabling circuit designers to optimise circuit layouts and utilise grounded heat sinks for safety.

ORDERING INFORMATION

Order As:

DIM750ASM65-TS000

Note: When ordering, please use the complete part number

KEY PARAMETERS

VCES		6500V
V _{CE(sat)}	* (typ)	2.8V
lc	(max)	750A
I _{C(PK)}	(max)	1500A

* Measured at the auxiliary terminals

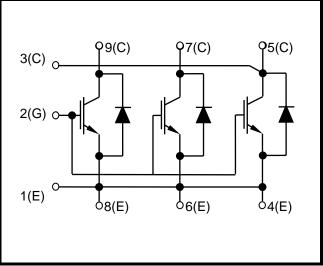


Fig. 1 Circuit configuration



Caution: This device is sensitive to electrostatic discharge. Users should follow ESD handling procedures

ABSOLUTE MAXIMUM RATINGS

Stresses above those listed under 'Absolute Maximum Ratings' may cause permanent damage to the device. In extreme conditions, as with all semiconductors, this may include potentially hazardous rupture of the package. Appropriate safety precautions should always be followed. Exposure to Absolute Maximum Ratings may affect device reliability.

T_{case} = 25°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
		$V_{GE} = 0V, T_j = 125^{\circ}C$	6500	V
VCES	Collector-emitter voltage	$V_{GE} = 0V, T_j = 25^{\circ}C$	6500	V
		$V_{GE} = 0V, T_j = -40^{\circ}C$	6000	V
V _{GES}	Gate-emitter voltage		±20	V
lc	Continuous collector current	T _{case} = 100°C	750	А
I _{C(PK)}	Peak collector current	1ms, T _{case} = 115°C	1500	А
P _{max}	Max. transistor power dissipation	$T_{case} = 25^{\circ}C, T_{j} = 125^{\circ}C$	11.1	kW
l ² t	Diode l ² t value	$V_R = 0, t_p = 10ms, T_j = 125^{\circ}C$	400	kA ² s
V _{isol}	Isolation voltage – per module	Commoned terminals to base plate. AC RMS, 1 min, 50Hz	10.2	kV
QPD	Partial discharge – per module	IEC1287, $V_1 = 6900V$, $V_2 = 5100V$, $50Hz$ RMS	10	рС

THERMAL AND MECHANICAL RATINGS

Internal insulation material:	AIN
Baseplate material:	AISiC
Creepage distance:	56mm
Clearance:	26mm
CTI (Comparative Tracking Index):	>600

Symbol	Parameter	Test Conditions	Min	Тур.	Мах	Units
Rth(j-c)	Thermal resistance – transistor	Continuous dissipation – junction to case			9	°C/kW
Rth(j-c)	Thermal resistance – diode	Continuous dissipation – junction to case			18	°C/kW
R _{th(c-h)}	Thermal resistance – case to heatsink	Mounting torque 5Nm (with mounting grease)			6	°C/kW
T _j J	Junction temperature	Transistor			125	°C
		Diode			125	°C
T _{stg}	Storage temperature range		-40		125	°C
		Mounting – M6			5	Nm
	Screw torque	Electrical connections – M4			2	Nm
		Electrical connections – M8			10	Nm

ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise.

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
	0 H + + + # + +	$V_{GE} = 0V, V_{CE} = V_{CES}$			4	mA
I _{CES}	Collector cut-off current	$V_{GE} = 0V, V_{CE} = V_{CES}, T_{case} = 125^{\circ}C$			90	mA
IGES	Gate leakage current	$V_{GE} = \pm 20V, V_{CE} = 0V$			1	μA
V _{GE(TH)}	Gate threshold voltage	$I_C = 120 \text{mA}, V_{GE} = V_{CE}$	5.5	6.5	7.5	V
M	Collector-emitter saturation	V _{GE} = 15V, I _C = 750A		2.8		V
V _{CE(sat)}	voltage	$V_{GE} = 15V, I_C = 750A, T_j = 125^{\circ}C$		3.7		V
lF	Diode forward current	DC			750	А
Іғм	Diode maximum forward current	t _p = 1ms			1500	А
M	Diada forward valtage	I _F = 750A		2.9		V
Vf	Diode forward voltage	$I_F = 750A, T_j = 125^{\circ}C$		3.4		V
Cies	Input capacitance	$V_{CE} = 25V$, $V_{GE} = 0V$, $f = 1MHz$		120		nF
Qg	Gate charge	±15V		10		μC
Cres	Reverse transfer capacitance	$V_{CE} = 25V, V_{GE} = 0V, f = 1MHz$		2.3		nF
Lм	Module inductance			10		nH
RINT	Internal resistance			90		μΩ
SC _{Data}	Short circuit current, Isc	$\begin{array}{l} T_{j} = 125^{\circ}C, \ V_{CC} = 4400V \\ t_{p} \leq 10 \mu s, \ V_{GE} \leq 15V \\ V_{CE \ (max)} = V_{CES} - L^{*} \ x \ dl/dt \\ IEC \ 60747-9 \end{array}$		3700		A

Note:

 * L is the circuit inductance + LM

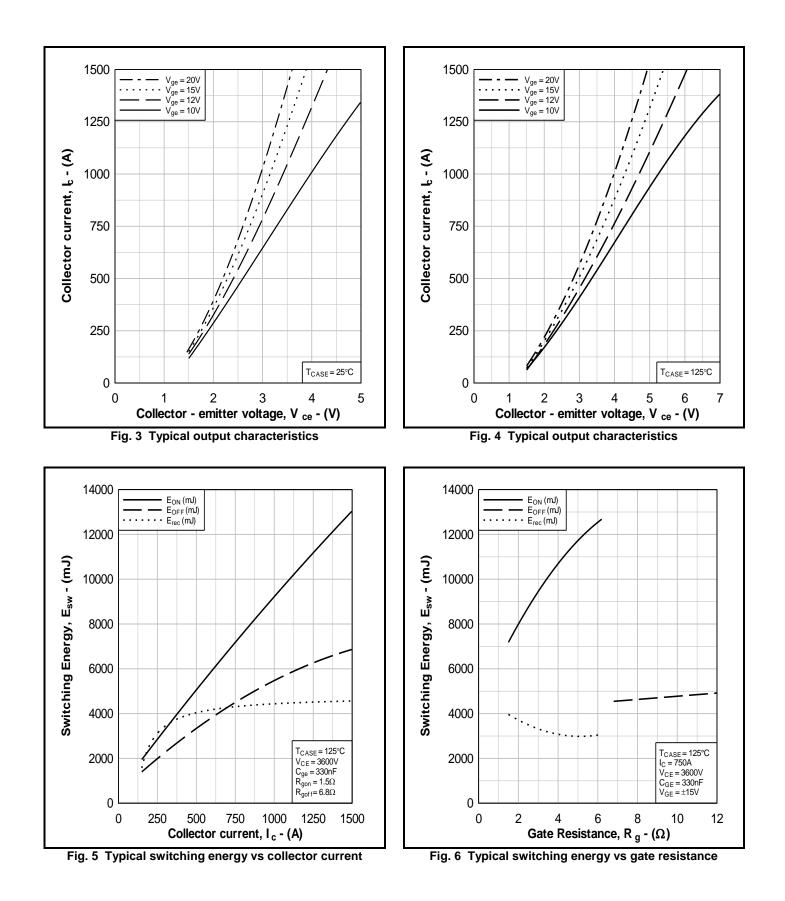
ELECTRICAL CHARACTERISTICS

T_{case} = 25°C unless stated otherwise

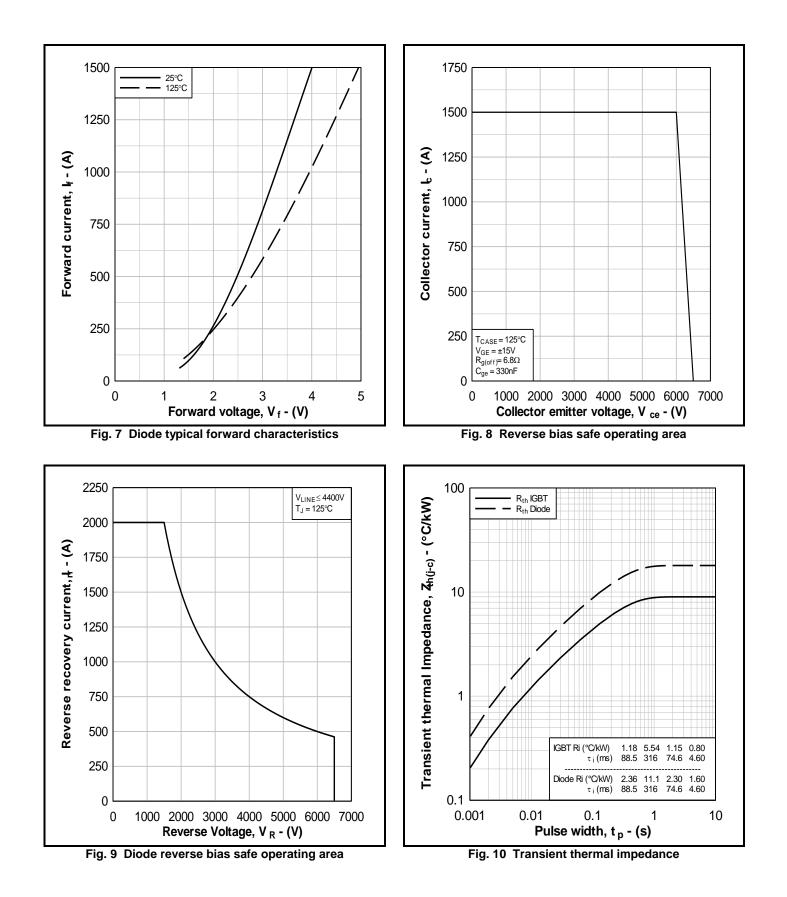
Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time	I _C = 750A		3700		ns
t _f	Fall time	$V_{GE} = \pm 15V$		450		ns
Eoff	Turn-off energy loss	$V_{CE} = 3600V$		4400		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 1.5\Omega$ $R_{G(OFF)} = 6.8\Omega$		620		ns
tr	Rise time	C _{ge} = 330nF		340		ns
Eon	Turn-on energy loss	L _s ~ 200nH		5850		mJ
Qrr	Diode reverse recovery charge	Diode arm		1500		μC
Irr	Diode reverse recovery current	IF = 750A VCE = 3600V		1550		А
Erec	Diode reverse recovery energy	dl⊧/dt = 4000A/µs		2700		mJ

T_{case} = 125°C unless stated otherwise

Symbol	Parameter	Test Conditions	Min	Тур.	Max	Units
t _{d(off)}	Turn-off delay time	lc = 750A		3900		ns
t _f	Fall time	$V_{GE} = \pm 15V$		450		ns
Eoff	Turn-off energy loss	V _{CE} = 3600V		4500		mJ
t _{d(on)}	Turn-on delay time	$R_{G(ON)} = 1.5\Omega$ $R_{G(OFF)} = 6.8\Omega$		550		ns
tr	Rise time	C _{ge} = 330nF		300		ns
Eon	Turn-on energy loss	Ls ~ 200nH		7100		mJ
Qrr	Diode reverse recovery charge	Diode arm		2500		μC
Irr	Diode reverse recovery current	I _F = 750A V _{CF} = 3600V		2350		А
Erec	Diode reverse recovery energy	dl⊧/dt = 4200A/µs		4300		mJ



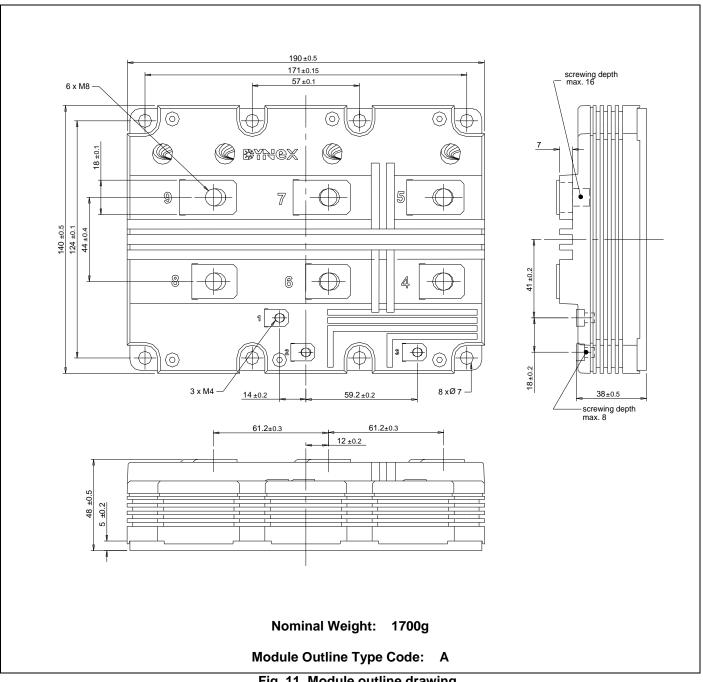
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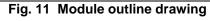


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PACKAGE DETAILS

For further package information, please visit our website or contact Customer Services. All dimensions in mm, unless stated otherwise. **DO NOT SCALE.**





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